

IN THE SPECIFICATION

Please amend the paragraph beginning at page 14, line 14 as follows:

To accurately locate the openings, one or more datums (~~not shown~~ 805) are precisely located on the wafer surface. The adhesive layer is chemically or manually removed (in the vicinity of these datums) to expose the datums. The masking apparatus then uses these datums to ensure accurate alignment of the openings 820 with the pads 808. Other methods of aligning the openings 820 are also possible within the scope of the invention.